

name of first joint inventor: Warren M. Farnworth
inventor's signature: *Warren M. Farnworth*
residence: Nampa, Idaho
citizenship: U.S.A.
Office Address: 2004 S. Banner, Nampa, Idaho 83686-7271

DECLARATION FOR PATENT APPLICATION
(continuation page)

Invention title: SEMICONDUCTOR DEVICE INCLUDING COMBED BOND PAD OPENING, ASSEMBLIES AND METHODS

Inventor name(s) appearing on first declaration page: Warren M. Farnworth

Additional original, first and joint inventor(s):

Name of second joint inventor: Walter L. Moden

Inventor's signature

Date

12-30-97

Residence: Meridian, Idaho

Citizenship: U.S.A.

Office Address: 622 Woodbury, Meridian, Idaho 83642

Name of third joint inventor: Larry D. Kinman

Inventor's signature

Date

12/30/97

Residence: Boise, Idaho

Citizenship: U.S.A.

Office Address: 11C33 Box 2461, Boise, Idaho 83706-9736

0992478 "031301"